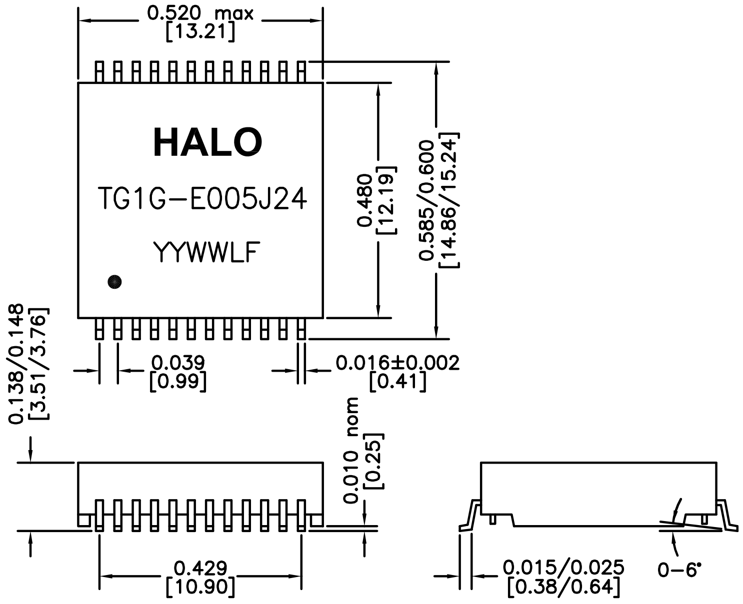
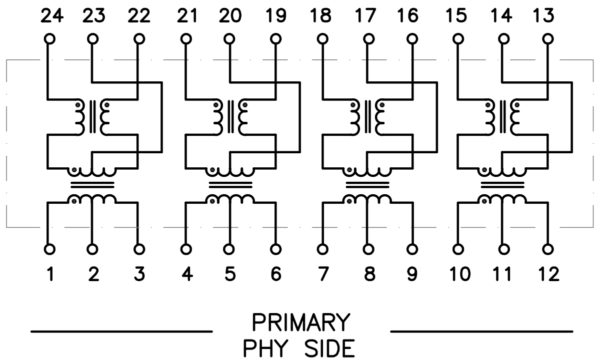
US PATENT NO. 5,656,985 6,297,720B1 6,297,721B1
6,320,489B1 6,344,785B1 6,662,431B1



DIMENSIONS: Inch [mm]
CO–PLANARITY: 0.004 [0.10]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



PART NO. : TG1G-E005J24LF

DESIGNED FOR DUAL–PORT FAST ETHERNET OR SINGLE–PORT GIGABIT ETHERNET APPLICATIONS

LEAD–FREE/RoHS COMPLIANT

COMPATIBLE TO LEAD–FREE SOLDERING PROCESS CONDITION PER IPC/JEDEC J–STD–020C

EXTENDED OPERATING TEMPERATURE –40/+85°C*

ELECTRICAL SPECIFICATIONS @ 25°C

TURNS RATIO	1CT:1CT ±3%
OCL (100KHz,0.1V,8mA)	350μH min
DCR (PRI)	1.3Ω max
LL (1MHz,0.1V)	0.4μH max
Cw/w	30pF max
INSERTION LOSS	
1–100MHz	–1.1dB max
RETURN LOSS	
0.5–40MHz	–18dB min
60MHz	–14dB min
80MHz	–12dB min
100MHz	–10dB min
CROSSTALK 1–100MHz	–40dB typ
CMR 1–100MHz	–40dB typ
ISOLATION	1,500Vrms

* TRANSFORMER MODULE WILL FUNCTIONAL WORK FROM –55°C TO +85°C WITH MINIMUM 120uH OCL

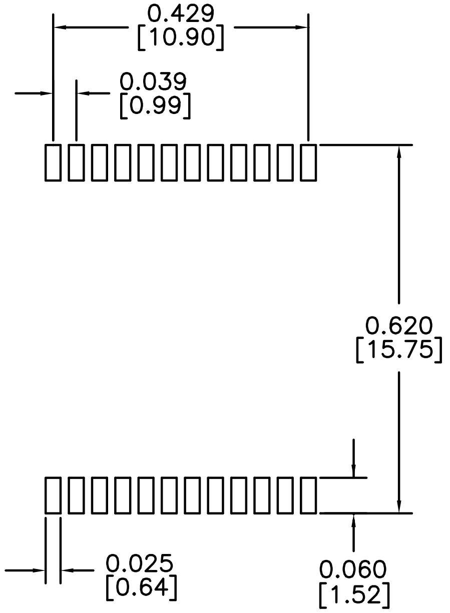
HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION MODULE
FOR	10/100/1000BASE–T
PART NO.	TG1G–E005J24LF
SCALE	NONE
PAGE	1 OF 2

SIGNATURES		DATE
DRAWN	LI ZHI ZHONG	11/16/15
CHECKED	LEI KEONG	12/19/17
APPROVED	PETER LU	12/19/17
FILE	E005J24LF.DWG	

REV.	DESC.	DATE
A	FIRST ISSUE	11/16/15
B	PROD. RELEASE	2/1/16
C	ADD TEMP. NOTE	12/19/17



RECOMMENDED PAD DIMENSIONS
DIMENSIONS: Inch [mm]

HALO/PBL	TITLE	ISOLATION MODULE		SIGNATURES	DATE	REV.	DESC.	DATE
	FOR	10/100/1000BASE–T		DRAWN LI ZHI ZHONG	11/16/15	A	FIRST ISSUE	11/16/15
CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE	PART NO.	TG1G–E005J24LF		CHECKED LEI KEONG	12/19/17	B	PROD. RELEASE	2/1/16
				APPROVED PETER LU	12/19/17	C	ADD TEMP. NOTE	12/19/17
	SCALE	NONE	PAGE 2 OF 2	FILE E005J24LF.DWG				